

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1500	(((passive or capacitor or induct\$3 or resist\$3) same (board or substrate or wafer or base)) and ((board or substrate or wafer or base) same (chip or die or "IC"))).clm.	US-PGPUB	OR	ON	2006/04/10 18:21
L2	573	1 and ((wir\$3 or conduct\$3) with (passive or capacit\$3 or induct\$3 or resist\$3)).clm.	US-PGPUB	OR	ON	2006/04/10 18:20
L3	275	2 and ((pad or terminal or electrode) with (passive or capacit\$3 or induct\$3 or resist\$3)).clm.	US-PGPUB	OR	ON	2006/04/10 18:20
L4	249	3 and (((passive or capacitor or induct\$3 or resist\$3) with (board or substrate or wafer or base)) and ((board or substrate or wafer or base) with (chip or die or "IC"))).clm.	US-PGPUB	OR	ON	2006/04/10 18:22
L5	83	4 and flip\$	US-PGPUB	OR	ON	2006/04/10 18:24
L6	1822	257/724.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/10 18:44
S1	1	"20040056341"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/10 14:58
S2	72	endo-mitsuyoshi.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/05/13 16:54
S3	68	matsuo-mie.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/05/13 16:54
S4	46	takubo-chiaki.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/05/13 16:54
S5	177	S2 S3 S4	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/05/13 16:55
S6	1	"2003007971"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/05/13 17:29
S7	1	"2002110865"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/05/13 17:28
S8	75	S5 and (passive or capacit\$4 or resist\$4 or induct\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/05/13 17:34
S9	45	S8 and (board or substrate) and (chip or die or "IC")	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/10 18:14

## EAST Search History

S10	15	S9 and (flip-chip or (flip adj chip))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/05/13 17:31
S11	10019	(passive or capacit\$4 or resist\$4 or induct\$4) and (board or substrate) and (chip or die or "IC") and (semiconductor) and (flip-chip or (flip adj chip))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/05/13 18:19
S12	434	S11 and (passive adj element) and (chip or die or "IC")	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/05/13 17:47
S13	4	((("5646830") or ("6066937") or ("4945399") or ("6611057"))).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/05/13 17:54
S14	1	("6166937").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/05/13 17:55
S15	1	S2 and ((bypass or decoupl\$4 or coupl\$4) near3 capacitor)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/05/13 17:57
S16	63	S12 and ((bypass or decoupl\$4 or coupl\$4) near3 capacitor)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/05/13 18:18
S17	57	S16 and (pad or terminal or connect\$4) and (wir\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/05/13 18:16
S18	6	S16 not S17	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/05/13 18:16
S19	371	S12 not S16	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/05/13 18:18
S20	19	S19 and ((passive or capacit\$4 or resist\$4 or induct\$4)).ti.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/05/13 18:19
S21	20	("5369249"   "5446311"   "5497033"   "5541135"   "5611008"   "5670824"   "5717245"   "5752182"   "5770476"   "5798567"   "5821627"   "5841194"   "5898223"   "5914535"   "6050829"   "6052287"   "6159817"   "6169329"   "6180445"   "6218729").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/13 18:30
S22	20	("5369249"   "5446311"   "5497033"   "5541135"   "5611008"   "5670824"   "5717245"   "5752182"   "5770476"   "5798567"   "5821627"   "5841194"   "5898223"   "5914535"   "6050829"   "6052287"   "6159817"   "6169329"   "6180445"   "6218729").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/13 18:31
S23	18	("6362525").URPN.	USPAT	OR	ON	2005/05/13 18:31
S24	19	"6362525"	USPAT	OR	ON	2005/05/13 18:31

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S25	20	("5369249"   "5446311"   "5497033"   "5541135"   "5611008"   "5670824"   "5717245"   "5752182"   "5770476"   "5798567"   "5821627"   "5841194"   "5898223"   "5914535"   "6050829"   "6052287"   "6159817"   "6169329"   "6180445"   "6218729"). PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/13 18:36
S26	14	(US-20040033654-\$ or US-20040053444-\$ or US-20040056341-\$ or US-20040238934-\$ or US-20050037535-\$ or US-20050093095-\$).did. or (US-4945399-\$ or US-5646830-\$ or US-5731747-\$ or US-6166937-\$ or US-6219254-\$ or US-6362525-\$ or US-6858892-\$ or US-6875638-\$).did.	US-PGPUB; USPAT	OR	ON	2005/11/14 18:49
S27	2	S26 and (active adj element)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/11/14 19:16
S28	1	S26 and (passive adj circuit)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/11/14 19:16
S29	14	(US-20040033654-\$ or US-20040053444-\$ or US-20040056341-\$ or US-20040238934-\$ or US-20050037535-\$ or US-20050093095-\$).did. or (US-4945399-\$ or US-5646830-\$ or US-5731747-\$ or US-6166937-\$ or US-6219254-\$ or US-6362525-\$ or US-6858892-\$ or US-6875638-\$).did.	US-PGPUB; USPAT	OR	ON	2005/11/15 11:14
S30	4	S29 and (semiconductor near2 (inductor or capacitor))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/11/15 11:14
S31	4	S29 and ((silicon or semiconductor) near2 (inductor or capacitor))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/11/15 11:19
S32	1863	((silicon or semiconductor) adj (inductor or capacitor))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/11/15 11:20
S33	74	S32 and (chip or die or "IC") and (flipchip or (flip adj chip))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/11/15 11:20
S34	71	S33 and (pad or solder or solderball or ball or bump)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/11/15 11:21
S35	66	S33 and (solder or solderball or ball or bump)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/11/15 11:21
S36	65	S35 and (CWB or board or wafer or substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/11/15 11:22
S37	60	S36 and (resin or paste or polyimide or polym\$3 or epoxy)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/11/15 11:22

## EAST Search History

S38	57	S37 and wir\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/11/15 11:23
S40	49	S38 and (@ad<"20020919" or @rlad<"20020919")	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/11/15 11:24
S42	1863	((silicon or semiconductor) adj (inductor or capacitor))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/11/15 11:39
S43	74	S42 and (chip or die or "IC") and (flipchip or (flip adj chip))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/11/15 11:39
S44	66	S43 and (solder or solderball or ball or bump)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/11/15 11:39
S45	65	S44 and (CWB or board or wafer or substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/11/15 11:39
S46	60	S45 and (resin or paste or polyimide or polym\$3 or epoxy)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/11/15 11:39
S47	57	S46 and wir\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/11/15 11:39
S48	49	S47 and (@ad<"20020919" or @rlad<"20020919")	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/11/15 11:39
S49	19	S48 and (package or shield\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/11/15 11:39
S50	2	"20020180027"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/10 15:10
S51	2	"6693362"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/10 15:10
S52	4	("4744008"   "5562971"   "5931222"   "6324067").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/10 15:15
S53	1	("6693362").URPN.	USPAT	OR	ON	2006/04/10 15:16

## EAST Search History

S54	6429	257/379,516,528-534,904,924,e27.033-e27.035,e27.113,e27.114.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/10 18:43
S56	436	H01L23/48.IPC.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/10 15:19
S57	23	H05K7/02.IPC.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/10 15:19
S58	3950	(S54 S56 S57) and ((passive or capacitor or induct\$3 or resist\$3) same (board or substrate or wafer or base))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/10 18:13
S59	3283	S58 and ((passive or capacitor or induct\$3 or resist\$3) with (board or substrate or wafer or base))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/10 15:22
S60	1041	S59 and ((chip or die or "IC") with (board or substrate or wafer or base))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/10 15:22
S61	900	S60 and (@ad<"20030917" or @rlad<"20030917")	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/10 15:28
S62	530	S61 and wir\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/10 15:24
S64	129	S62 and flip\$	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/10 15:24
S65	107	S64 and thickness	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/10 15:25
S66	91	S65 and (@ad<"20020919" or @rlad<"20020919")	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/10 15:28
S67	4	("4577214"   "4907062"   "5440171"   "5608261").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/10 15:38
S68	10	("5729053").URPN.	USPAT	OR	ON	2006/04/10 15:39